

METHOD OF MOUNTING ELECTRONIC PARTS ON WIRING BOARD

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ABSTRACT OF THE DISCLOSURE

10 A method of mounting electronic parts, on a wiring board, is provided in which a bare chip is bonded to connecting pads via thin solder layers by means of flip chip bonding and at least another soldered part is soldered to a mounting pad on the board via a thin solder layer. First, adhesive resin layers are formed on the connecting pads and the mounting pad. Solder particles
15 are scattered so that the solder particles temporarily adhere to the connecting pads and the mounting pad. The soldering part is put on the mounting pad and a reflow process is conducted so that the solder particles are made to reflow to pre-coat the connecting pads with a
20 thin solder layer and, simultaneously, the soldered part is mounted on the mounting pad via solder. Finally, the bare chip is positioned on the thin solder layer of the connecting pads and a flip-chip bonding process is conducted by which the bare chip is flip-chip bonded to
25 the connecting pads.